

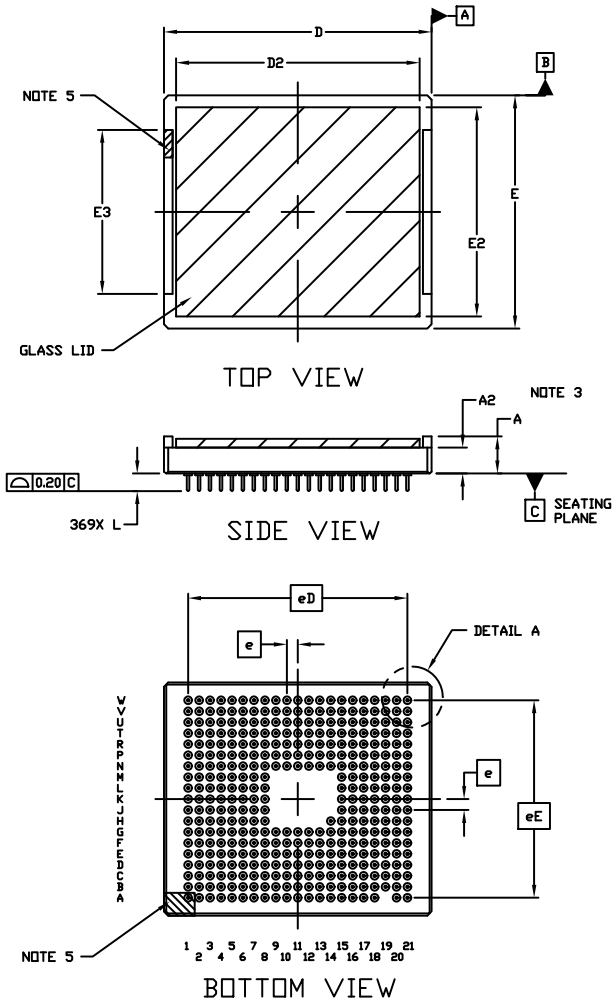
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



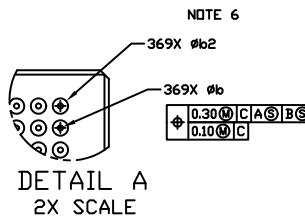
CPGA369, 31.00x27.00
CASE 107DK-01
ISSUE O

DATE 06 JUL 2011



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
5. PIN A1 IDENTIFICATION WILL BE IN THESE AREAS. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.
6. THIS DIMENSION DEFINES THE MAXIMUM SIZE FOR THE PIN BRAZE PADS.

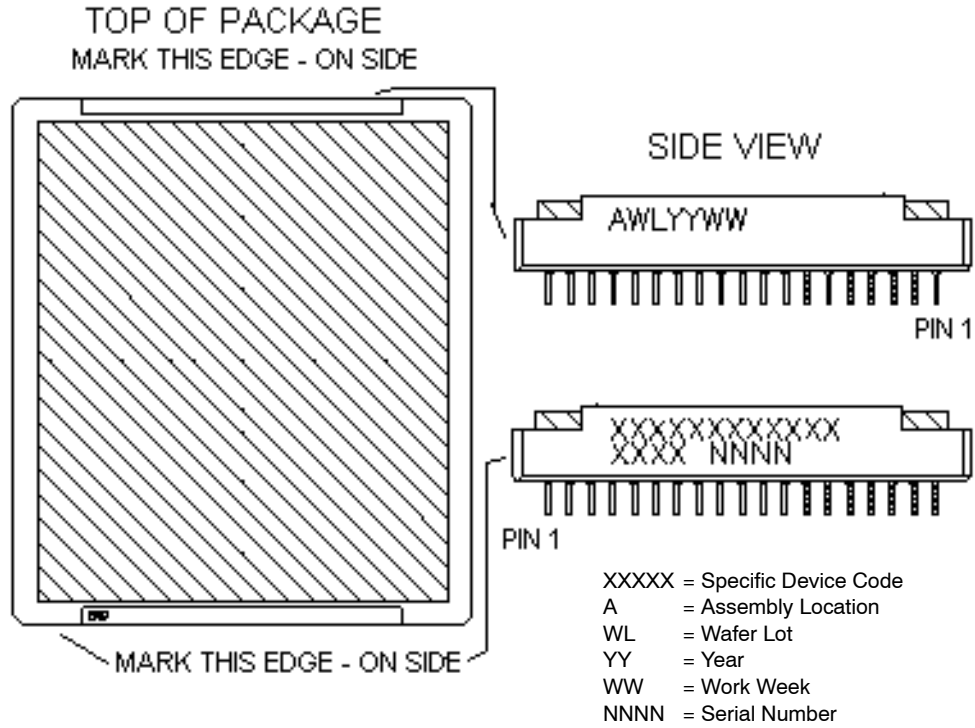


DIM	MILLIMETERS	
	MIN.	MAX.
A	3.87	4.73
A2	2.57	3.43
b	0.25	0.35
D	---	1.05
D2	30.69	31.31
E	26.73	27.27
E2	24.20	REF
E3	19.00	REF
e	1.27	BSC
eD	25.40	BSC
eE	22.86	BSC
L	1.80	2.20

GENERIC MARKING
DIAGRAM ON PAGE 2

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**GENERIC
MARKING DIAGRAM**



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